

法人說明會

Investor Conference

2025.03.27

GMM



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This presentation contains some forward-looking statements that are subject to substantial risks and uncertainties. Typically, these statements contain words such as “anticipate” , “believe”, “could”, “estimate”, “expect”, “intend”, “plan” , “forecast” , “project”, “predict”, “potential”, “continue”, “may” , “should” , “will”, and “would” or similar words. You should consider these forward-looking statements carefully because such statements are only our expectations or projections about future events, and actual results may differ materially from those expressed or implied by such statements. The forward-looking statements in this presentation include, but are not limited to, growth rates for various markets estimated by third party sources, future products and technology development, widespread market acceptance of the hosted delivery model, future revenue growth and profitability. You should be cautioned that the forward-looking statements are no guarantee of our future performance. The forward-looking statements contained in this presentation are made only as of the date of this presentation and we undertake no obligation to update the forward-looking statements to reflect subsequent events or circumstances, except as required by law.

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Alliance's Total Market Value: Exceeds **2 Billion** USD

The Alliance Members: 1,500⁺

R&D personnel: 500⁺

R&D personnel account for 33%



***c sun* 志聖**

Thermal (熱)
Bonder (壓合)
Lamination (貼膜)
Peeling (撕膜)
UV/Plasma (光/電漿)

GPM 均豪精密

AOI (檢測)
Metrology (量測)
Grinding (研磨)
Polishing (拋光)

GMM 均華精密

Die Attach (黏晶)
Chip Sorter (揀晶)
Auto Jig Saw (切單挑揀)

Alliance Synergy Core Technologies



Company History

- Established in 2010
- 2018 IPO (Stock Code : 6640)

Main Products

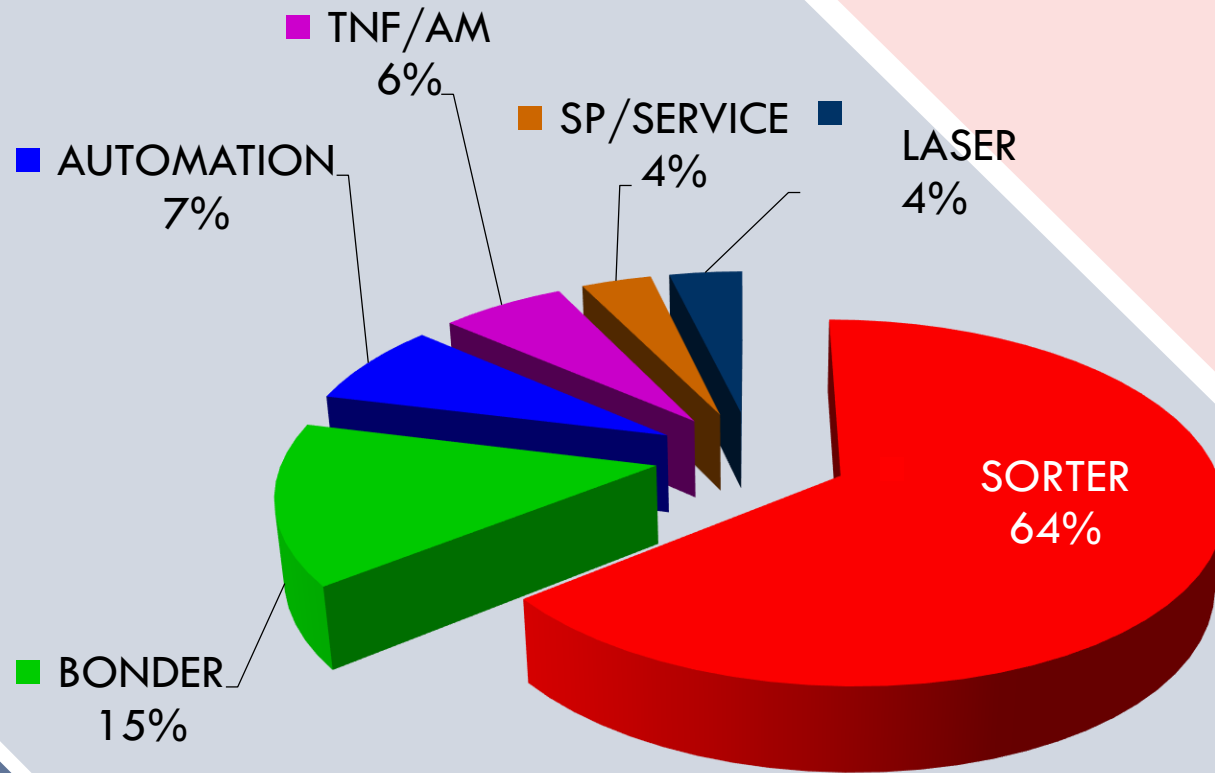
- Advanced Packaging Pick & Place
- Chip Sorter
 - Die Bonder

Business Locations

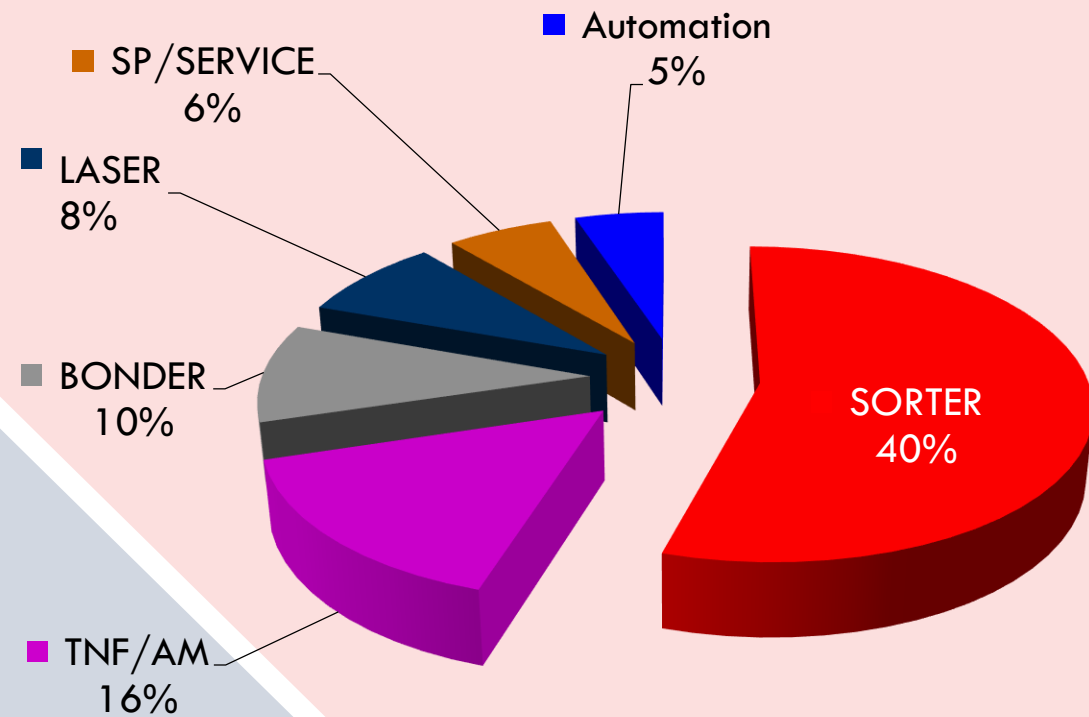
- Tucheng HQ
- Hsinchu
- Suzhou
- Taichung
- Kaohsiung

銷售分析

2024



2023

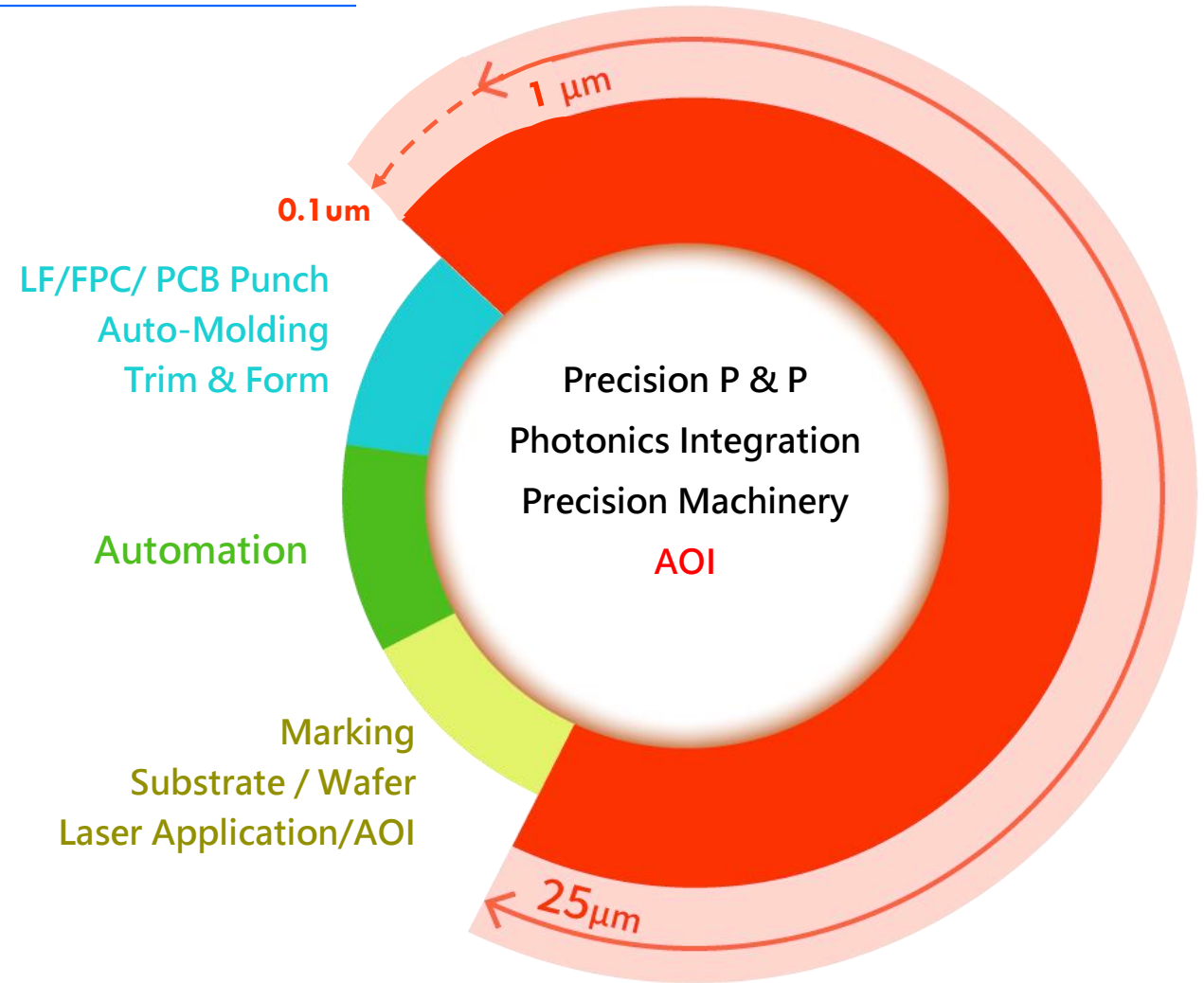


Key Value Technology

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AI Sorter for Known Good Die

6S Inspection Chip Sorter



Die Attach

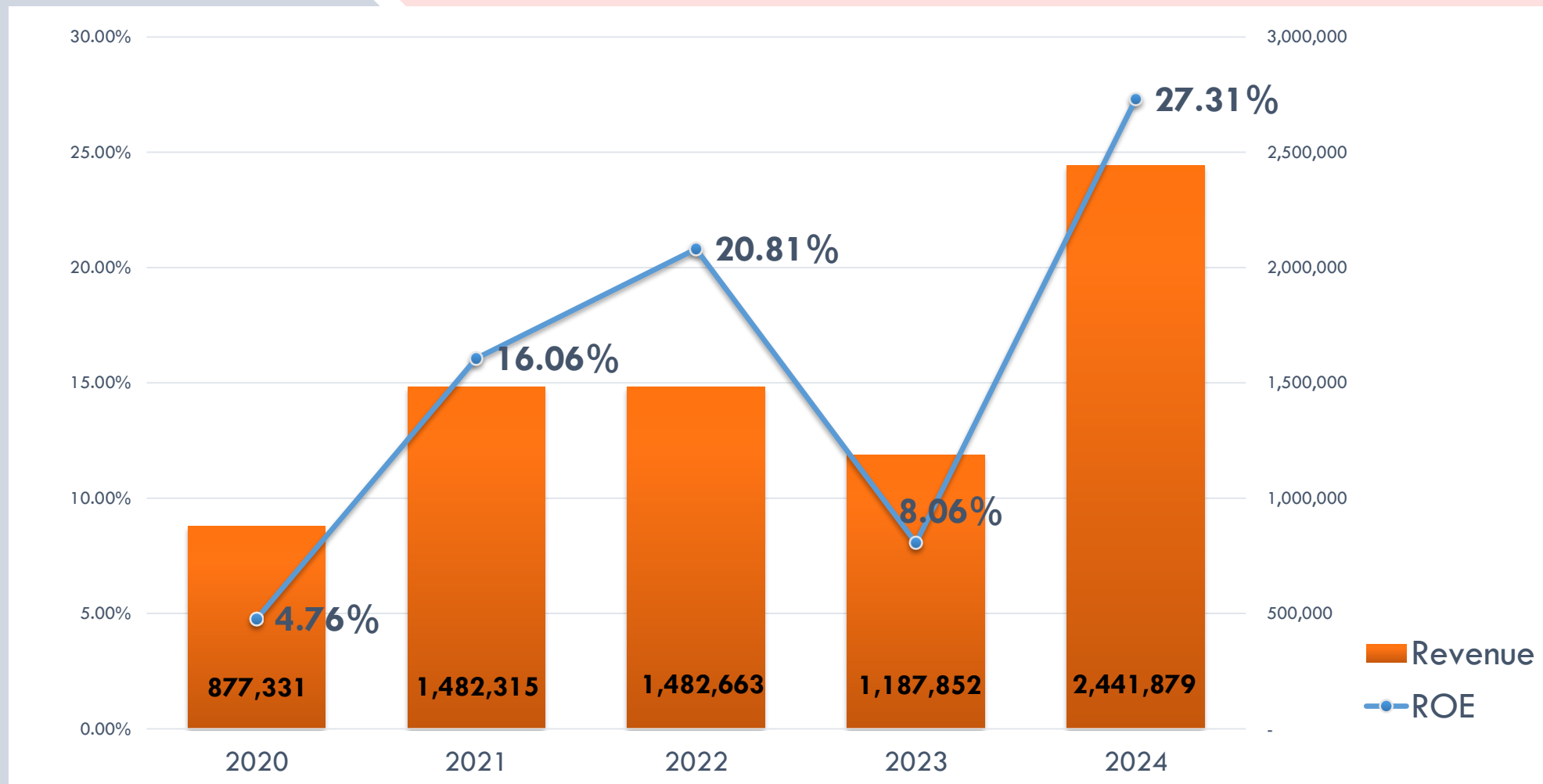
Die Bonder for Fan-out/ InFO/ CoWoS/ FOPLP

營運成果

in TWD 千元

Year	2024		2023		2022		2021		2020	
Accumulated	Amount	%	Amount	%	Amount	%	Amount	%	Amount	%
Revenue-Consolidated	2,441,879		1,187,852		1,482,663		1,482,315		877,331	
COGS	1,518,370	62.2%	776,443	65.4%	886,296	59.8%	978,554	66.0%	616,404	70.3%
Gross Margin	923,509	37.8%	411,409	34.6%	596,367	40.2%	503,761	34.0%	260,927	29.7%
Operating Expense	481,719	19.7%	292,573	24.6%	350,316	23.6%	342,765	23.1%	276,682	31.5%
Operating Income	441,790	18.1%	118,836	10.0%	246,051	16.6%	160,996	10.9%	- 15,755	-1.8%
Net Income before tax	520,335	21.3%	118,350	10.0%	298,745	20.1%	200,128	13.5%	58,453	6.7%
Net Income after tax	412,772	16.9%	100,857	8.5%	229,720	15.5%	157,506	10.6%	44,522	5.1%
ROE	27.31%		8.06%		20.81%		16.06%		4.76%	
EPS (NT\$/after tax)	\$14.62		\$3.57		\$8.33		\$5.84		\$1.57	
Debt Ratio	55.42%		61.26%		54.09%		59.36%		51.09%	

股東權益報酬率

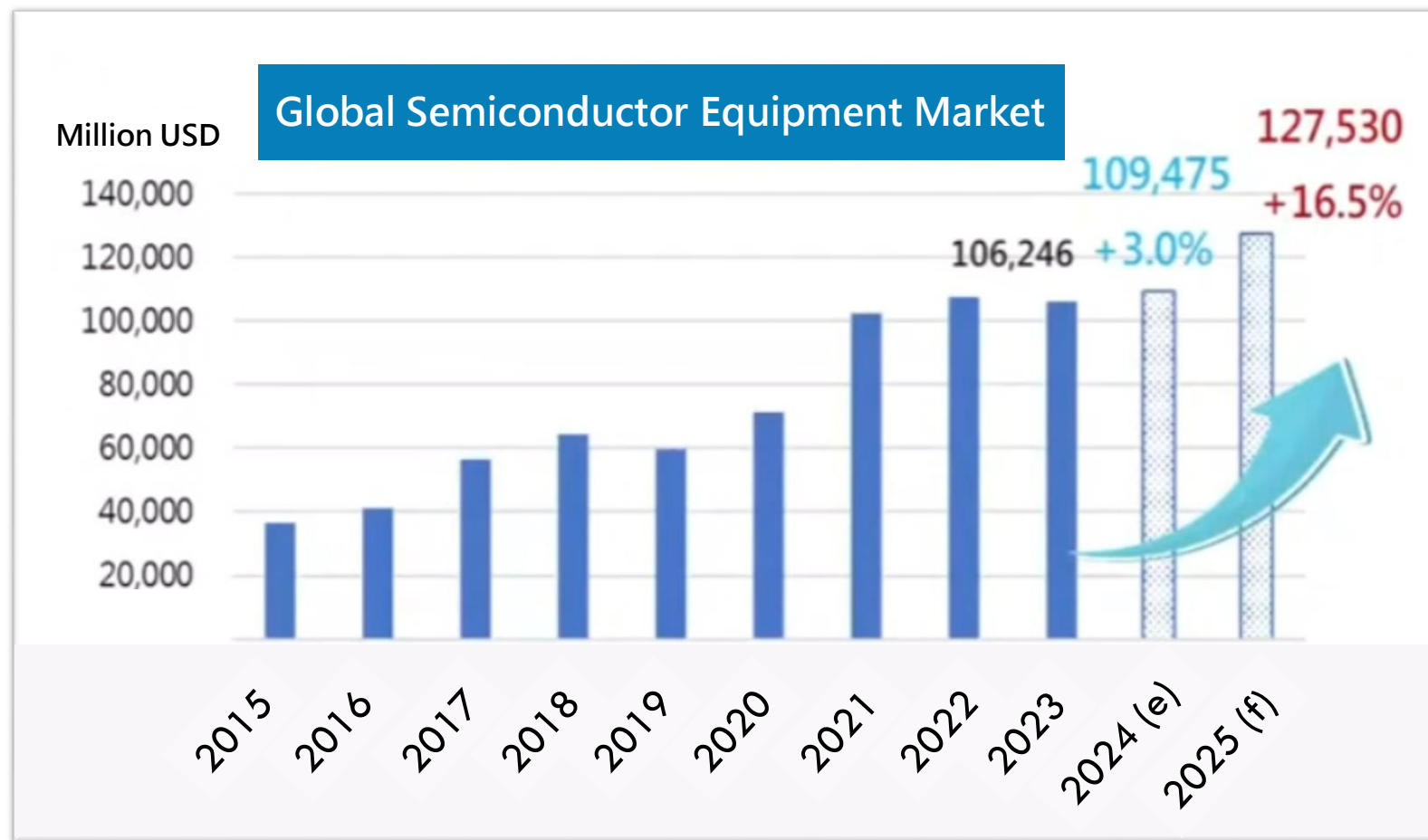


Unit: NTD thousands

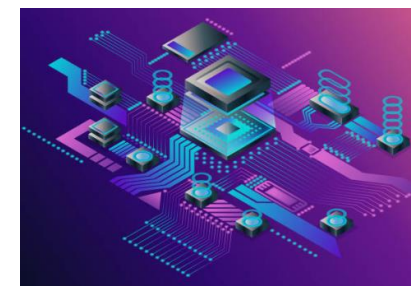
Year	2024	2023	YoY
Revenue-Consolidated	2,441,879	1,187,852	106%
Gross Margin	923,509	411,409	124%
Gross Margin %	37.82%	34.63%	3%
Operating Expense	481,719	292,573	65%
Operating Expense %	19.73%	24.63%	-5%
Operating Income	441,790	118,836	272%
Operating Income %	18.09%	10.00%	8%
Net Income before tax	520,335	118,350	340%
Net Income after tax	412,772	100,857	309%
Net Income after tax %	16.90%	8.49%	8%
EPS (NT\$/after tax)	14.62	3.57	310%

全球半導體設備成長趨勢

GMM



WSTS ; IEK



產品發展脈絡

Bonder/ Sorter
核心技術相輔相成

Sorter 佈局

- ✓ AOI 加值
- ✓ 樂高模組
- Sorter 市場延伸應用佔比極大化

Bonder
領軍系列產品

- ✓ EFEM、串機模組
- ✓ AOI應用

核心技術
延伸新產品

- ✓ Hybrid Bond 發展
- ✓ Jig Saw

2025展望

基於目前對營運展望的假設，

從Yole Group的預測，到2025年先進封裝市場的比重將突破傳統封裝，達到51.03%，

到一線晶圓/封裝廠預期市場將受惠於人工智慧(AI)和高效能運算(HPC)的需求攀升，

半導體產業持續大幅成長，同時半導體市場成長驅動力也主要在先進封裝製程較為成長強烈，

在原先進封裝製程需求持續向上跳躍前提，包含PLP、CPO也具較大的未來前景，

GMM為追求更多元的市場需求，2024與2023年相比增加了30%以上的研發工程人才，

也預期2025先進封裝製程產品出貨預期再創營收新高。





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Stock No.
2467.TW
c sun 志聖

6640.TW
GMM 均華

5443.TW
GPM 均豪